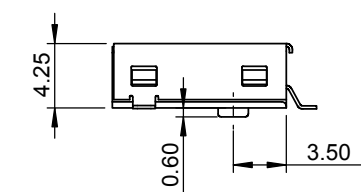
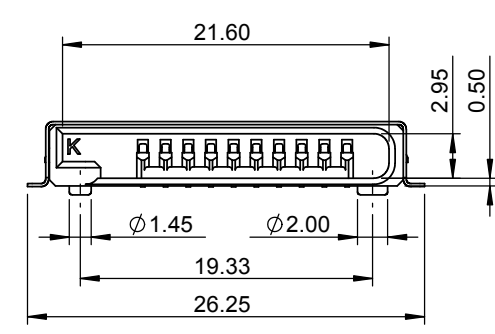
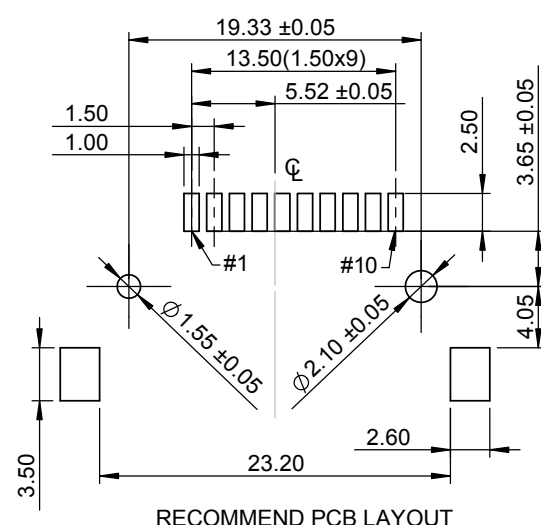
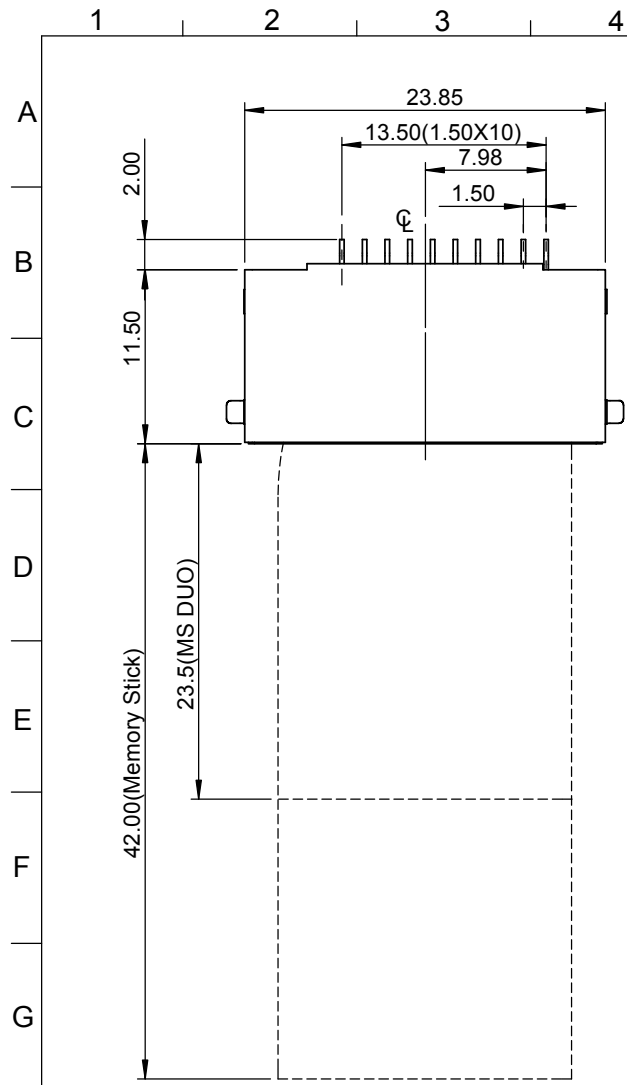


更改 REV	設 變 內 容 MODIFICATION
E	ECN00780
F	ECN00868
G	ECN02222
H	ECN03141
I	ECN04030

PIN DEFINITION

MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS

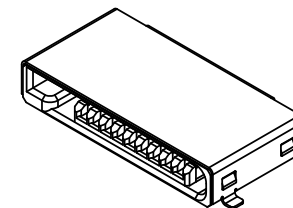
GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X±0.50	X°±5°	名稱(TITLE)	
.X±0.30	.X°±2°	MemoryStick & MemoryStick Duo CONNECTOR NORMAL TYPE	
.XX±0.20	.XX°±1°	圖 號(DWG NO.)	
單位(UNIT)	料 號(PART NO.)	7MSMS-XX-X0X1-I	
mm	7MSMS-XX-X0X1	7MSMS-XX-X0X1-I	
審核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE
			2:1
			張 數 SHEET
			1 / 2
			角 法 PROJ
			更 改 REV
			I



NOTES :
 1. MATERIAL :
 INSULATOR : HIGH TEMPRATURE THERMOPLASTIC,
 UL 94V-0, IVORY
 CONTACT : COPPER ALLOY
 2. APPLICATION:
 MS & MS Duo & MS PRO & MS PRO Duo &
 MagicGate MS Duo & MS I/O Expansion & MS-
 ROM & MS Duo-ROM & MagicGate MS
 3. PART NO : 7MSMS-XX-X0X1

0:WITHOUT LOGO
 1:WITH LOGO
 PACKING:
 0:TRAY
 1:REEL
 COLOR:
 0:BLACK
 9:IVORY
 PLATING:
 F: CONTACT AREA:GLOD FLASH Au PLATED OVER Ni
 SOLDER AREA: MATTE Tin PLATED OVER Ni
 B: CONTACT AREA:10µ" Au PLATED OVER Ni
 SOLDER AREA: MATTE Tin PLATED OVER Ni

更改 REV	設 變 內 容 MODIFICATION
E	ECN00780
F	ECN00868
G	ECN02222
H	ECN03141
I	ECN04030



PIN DEFINITION

MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS

PART NO. : 7MSMS-XX-X001

GENERAL TOLERANCE	
X ± 0.50	X ° ± 5°
.X ± 0.30	.X ° ± 2°
.XX ± 0.20	.XX ° ± 1°

KINGCONN 皇海科技股份有限公司	
名稱(TITLE) MemoryStick & MemoryStick Duo CONNECTOR NORMAL TYPE	

單位(UNIT) mm	料 號(PART NO.) 7MSMS-XX-X0X1	圖 號(DWG NO.) 7MSMS-XX-X0X1-I
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)
比 例 SCALE 2:1		張 數 SHEET 2 / 2
角 法 PROJ.		更 改 REV I

